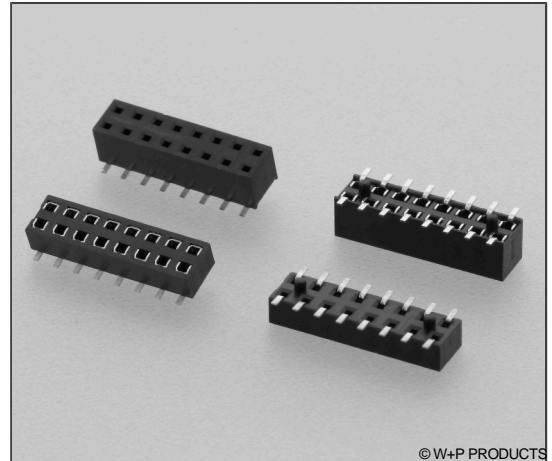


## SMT-Buchsenleisten RM 2,00mm, stehend, 2-reihig – durchsteckbar SMT Female Headers, 2.00mm Pitch, Vertical, Double Row – Pass Through

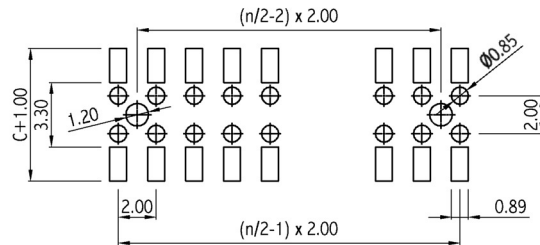
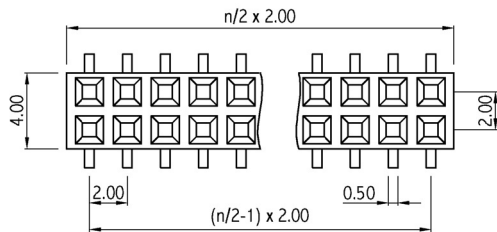
### Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Kontaktfläche <i>Contact Surface</i>	Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm) <i>Acc. to options (see below), over Ni (1.3 ... 2.5µm)</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ
Spannungsfestigkeit <i>Test Voltage</i>	500 V AC
Nennstrom <i>Current Rating</i>	1 A
Temperaturbereich <i>Temperature Range</i>	-40 °C ... +125 °C
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>



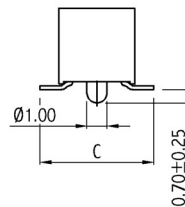
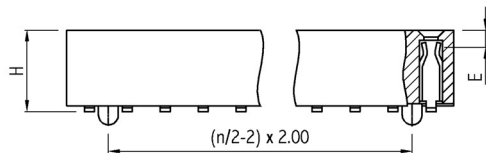
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Doppelfederkontakte für Vierkantstifte 0,50mm.  
Dual beam contacts accept 0.50mm square pins.



Type -20- / -30-

PCB Layout  
(for all Types)

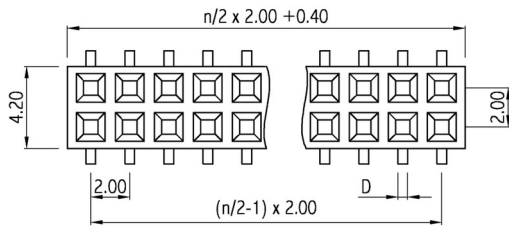


Type	H	C	E
20	4.30	6.00	1.20
30	3.70	6.40	1.30

<b>Series</b>	<b>Contacts*</b>	<b>Type*</b>	<b>Plating*</b>	<b>Locating Pegs*</b>	<b>Package*</b>
<b>7450</b>	<b>20</b>	<b>20</b>	<b>00</b>	<b>00</b>	<b>ST</b>
	04-80 Type 20 04-40 Type 30	20 H=4,3mm, Eingang oben H=4.3mm, top entry 30 H=3,7mm, Eingang oben H=3.7mm, top entry	00 Vergoldet Gold plated 50 Verzinkt Tin plated 60 Sel. Au/Sn Duplex plating	00 Ohne Pos.hilfen W/o loc. pegs 10 Mit Pos.hilfen (nur Type 20) With loc. pegs (only Type 20)	ST PPST PPTR

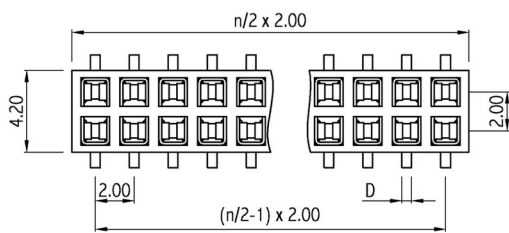
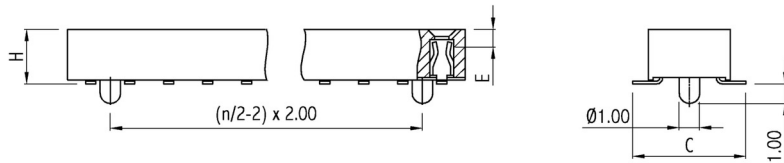
# 7450

**SMT-Buchsenleisten RM 2,00mm, stehend, 2-reihig – durchsteckbar**  
**SMT Female Headers, 2.00mm Pitch, Vertical, Double Row – Pass Through**

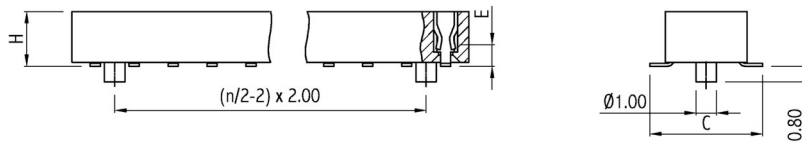


Type	H	C	D	E
10	2.80	5.80	0.50x0.15	0.90
11	2.80	5.80	0.50x0.15	1.10

Type -10-



Type -11-



Series	Contacts*	Type*	Plating*	Locating Pegs*	Packaging*
<b>7450</b>	<b>22</b> 04-80 Type 10/11	<b>10</b> 10 H=2,8mm, Eingang oben H=2.8mm, top entry 11 H=2,8mm, Eingang unten H=2.8mm, bottom entry	<b>00</b> Vergoldet Gold plated <b>50</b> Verzinkt Tin plated <b>60</b> Sel. Au/Sn Duplex plating	<b>10</b> Ohne Pos.hilfen W/o loc. pegs <b>10</b> Mit Pos.hilfen With loc. pegs	<b>ST</b> ST PPST PPTR

**Lieferformen / Packaging Options:**

**ST** In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads  
**PPST** In Stangen mit P&P-Pads / In tubes with P&P-Pads  
**PPTR** Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

\* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.  
 \* This is an **order example** - please replace by your specifications.

### Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150 °C
Temperatur Maximum $T_{Smax}$	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich $T_L$	217 °C
Verweildauer oberhalb $T_L$	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur $T_P$	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur $T_P$	max. 8m

### Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150 °C
Maximum Temperatur $T_{Smax}$	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature $T_L$	217 °C
Duration above $T_L$	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature $T_P$	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. $T_P$	max. 8min

